

APPROVAL SHEET

RFBPB 2012(0805) Series - RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

- Balanced Type

2.4 GHz ISM Band Working Frequency

P/N: RFBPB2012090AM1T61

*Contents in this sheet are subject to change without prior notice.

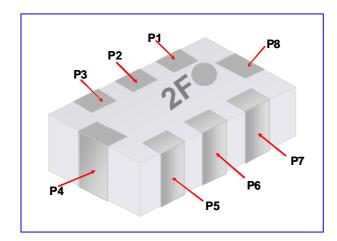
FRATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.9 mm³
- 2. Low Profile Thickness
- 3. Low Insertion loss
- 4. High Rejection Rate
- 5. High attenuation on 2nd harmonic suppressed
- 6. Allowable for DC biasing.
- 7. LTCC process

APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g/n, HomeRF

CONSTRUCTION



PIN	Definition	PIN	Definition
P1	Unbalance Port	P5	Balance Port
P2	DC/GND	P6	GND
Р3	NC	P7	Balance Port
P4	GND	P8	GND

DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	2.00 ± 0.15
2F •	W	1.25 ± 0.10
	Т	0.90 ± 0.10
	А	0.20 ± 0.15
F	В	0.30 ± 0.10
≥ □ □	С	0.35 ± 0.10
<u> </u>	D	0.65 ± 0.10
D C B A 1	E	0.20 ± 0.15
	F	0.20 ± 0.15
	G	0.30 ± 0.10

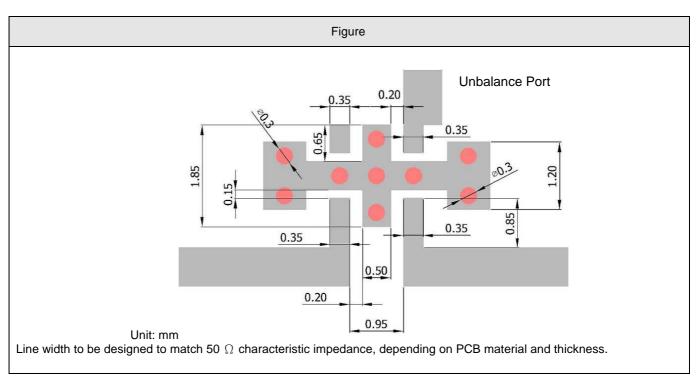


freq, GHz

ELECTRICAL CHARACTERISTICS

RFBPB2012090AM1T61	Specification		
Frequency range	2450 ± 50 MHz		
Insertion Loss	2.8 dB max		
VSWR	2.1 max		
Impedance (Unbalanced)	50 Ω		
Impedance (Balanced)	Conjugate match to MTK MT6611 Bluetooth chipset		
Phase Difference	180° ± 10°		
Amplitude Difference	2 .0 dB Max		
Attenuation (min.)	35dB @ 880~960 MHz 30dB @ 1710~1880 MHz 20dB @ 1880~1990 MHz 30dB @ 4800~5000 MHz		
Typical Electrical Chart			
-10 dB(m4 freq dB() m5 freq dB()	m1 freq=2.450GHz phase(S(3,5))=107.884 m2 freq=2.450GHz phase(S(3,4))=-73.567 100 phase(S(3,4))=-73.567		

SOLDER LAND PATTERN





RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≤0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency: 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude: 1.5mm	Samples shall satisfy electrical specification
	*Test times : 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	*Temperature: 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
11	·	
Humidity	*Humidity: 90% to 95% R.H.	No mechanical damage.
(steady conditions) JIS C 0022	*Temperature : 40±2°C	Samples shall satisfy electrical specification
310 0 0022	*Time: 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

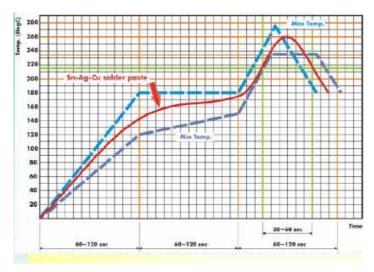


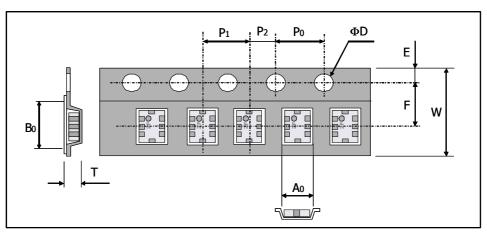
Fig 2. Infrared soldering profile

ORDERING CODE

RF	BPB	201209	0	Α	M1T61
Walsin	Product Code	Dimension code	Unit of dimension	Application	Specification
RF device	BPB:	Per 2 digits of Length,	0 : 0.1 mm	A: 2.4GHZ ISM	Design Code
	Balanced	Width, Thickness:	1 : 1.0 mm	Band	
	Type Band	e.g. :			
	Pass	201209 =			
	Filter	Length 20,			
		Width 12,			
		Thickness 9			

Minimum Ordering Quantity: 2000 pcs per reel.

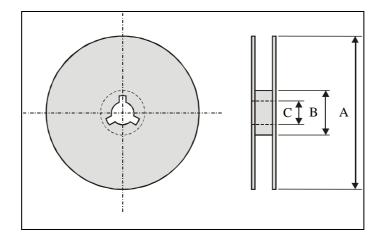
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	T	W
Dimension (mm)	1.45 ± 0.10	2.25 ± 0.10	1.55 ± 0.10	1.10 ± 0.10	8.00 ± 0.30
Index	Е	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	А	В	С
Dimension (mm)	Φ178	Φ60.0	Ф13.5

Typing Quantity: 2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity: 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.